



ITW

**PATENT APPLICATION**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of

Docket No: Q92997

Yasukazu NAKATA, et al.

Appln. No.: 10/567,358

Group Art Unit: Not Yet Assigned

Confirmation No.: 9855

Examiner: Not Yet Assigned

Filed: February 6, 2006

For: FLIP CHIP MOUNTING SUBSTRATE

**RESPONSE UNDER 37 C.F.R. § 1.111**

**MAIL STOP AMENDMENT**

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

Sir:

In response to the Office Action dated September 20, 2006, please consider the remarks  
as follows on the accompanying pages.

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